SURFACE MOUNT FAST SWITCHING DIODE ARRAY

Features

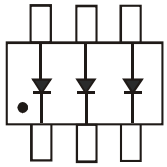
- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance
- **Lead Free/RoHS Compliant (Note 3)**
- **"Green" Device (Notes 4 and 5)**

Mechanical Data

- Case: SOT-26
- Case Material: Molded Plastic, "Green" Molding Compound, Note 5. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Copper leadframe).
- Orientation: See Diagram
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.016 grams (approximate)

SOT-26

TOP VIEW



TOP VIEW
Internal Schematic

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V_{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	80	V
RMS Reverse Voltage	$V_{R(RMS)}$	57	V
Forward Continuous Current (Note 1)	I_{FM}	500	mA
Average Rectified Output Current (Note 1)	I_O	250	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0μs @ t = 1.0s	I_{FSM}	4.0 2.0	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P_D	350	mW
Thermal Resistance Junction to Ambient Air (Note 1)	$R_{\theta JA}$	357	°C/W
Operating and Storage Temperature Range	T_J , T_{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	$V_{(BR)R}$	80	—	V	I_R = 2.5μA
Forward Voltage	V_F	0.62 — — —	0.72 0.855 1.0 1.25	V	I_F = 5.0mA I_F = 10mA I_F = 100mA I_F = 150mA
Reverse Current (Note 2)	I_R	—	100 50 30 25	nA μA μA nA	V_R = 70V V_R = 75V, T_J = 150°C V_R = 25V, T_J = 150°C V_R = 20V
Total Capacitance	C_T	—	3.5	pF	V_R = 6, f = 1.0MHz
Reverse Recovery Time	t_{rr}	—	4.0	ns	V_R = 6V, I_F = 5mA

Notes:
1. Device mounted on FR-5 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
2. Short duration pulse test used to minimize self-heating effect.
3. No purposefully added lead.
4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
5. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants

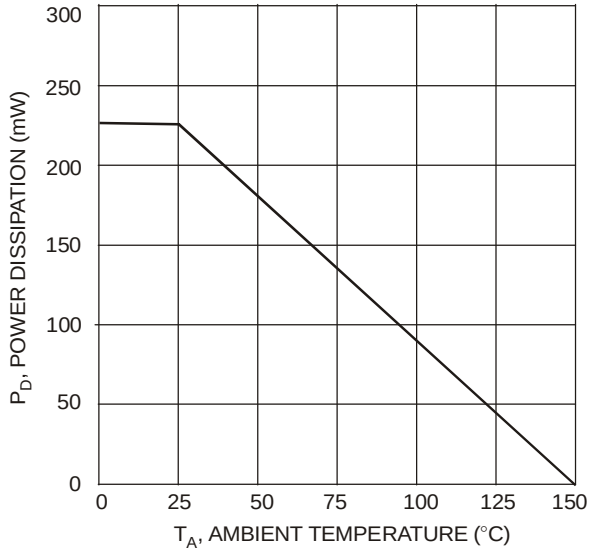


Fig. 1 Power Derating Curve, Total Package

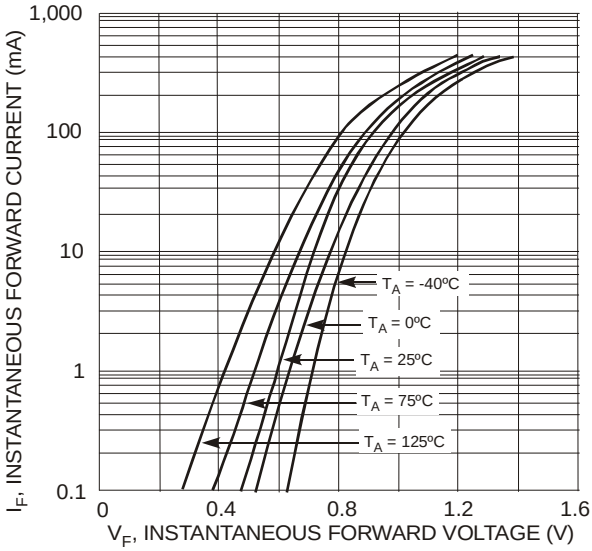


Fig. 2 Typical Forward Characteristics, Per Element

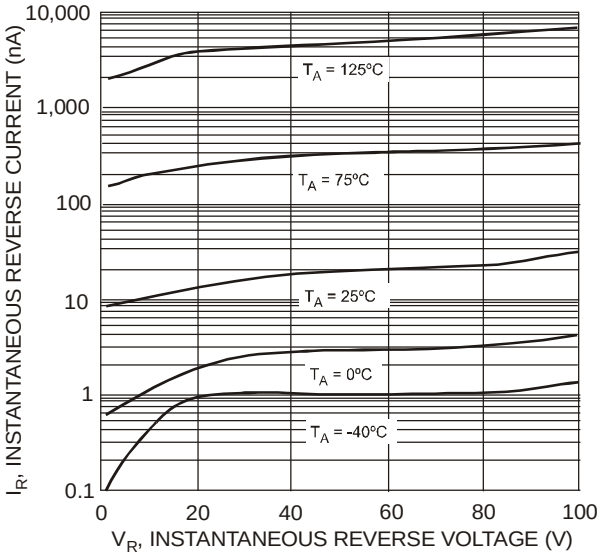


Fig. 3 Typical Reverse Characteristics, Per Element

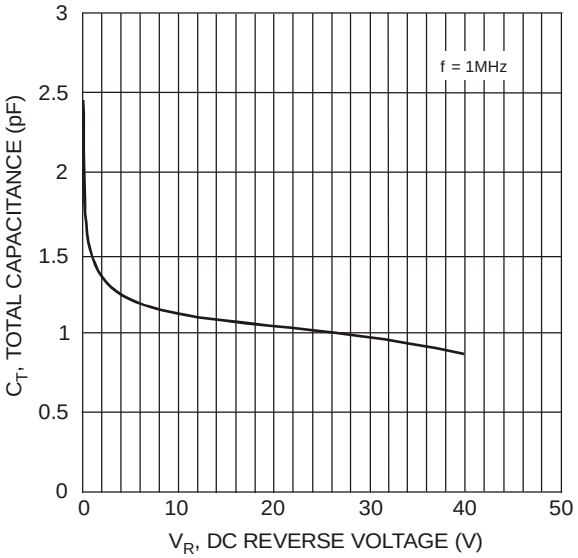


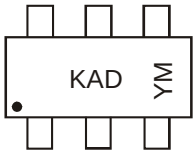
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Ordering Information (Notes 5 & 6)

Part Number	Case	Packaging
MMBD4448HTM-7-F	SOT-26	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



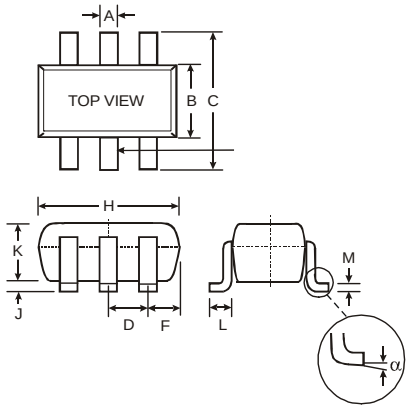
KAD = Product Type Marking Code
YM = Date Code Marking
Y =Year ex: T = 2006
M = Month ex: 9 = September

Date Code Key

Year	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	N	P	R	S	T	U	V	W	X	Y	Z

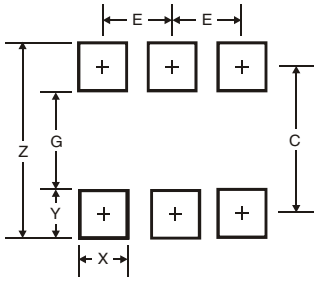
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-26			
Dim	**Min**	**Max**	**Typ**
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
F	—	—	0.55
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C	2.40
E	0.95